

Enhancement Mode N-Channel Power MOSFET

 $TO-252/NMOS/40V/\pm20V/1.6V/80A/5.8m\Omega$

Rev_{0.8}





40V, 5.8mΩ, 80A, N-Channel Enhancement MOSFET

1.Features

- ♦ 40V MOSFET technology
- ◆ Low on-state resistance
- Fast switching
- ♦ Vgs±20V
- ♦ 100% RG Tested
- ◆ 100% UIS Tested

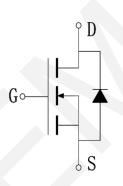
2.Applications

- Power Switching Application
- ◆ Load Switching



Pin Description

V _{DS}	R _{DS(on)} Typ.	I _D Max.	
40V	5.8mΩ @ 10V	004	
	7.3mΩ @ 4.5V	80A	



Schematic Diagram

3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP4070KA	WP4070KA	TO-252	2,500	25,000

4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V _{DSS}	40	V
Gate to Source Voltage	V _{GSS}	±20	V
Drain Current (DC)	I _D	80	А
Drain Current (Pulse), PW≤300μs	I _{DP}	320	А
Total Dissipation	P _D	120	W
Avalanche Energy, Single Pulsed	E _{AS}	144	mJ
Junction Temperature	Tj	150	°C
Storage Temperature	T_{stg}	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



5. Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Junction to Case	Rejc	1.25	°C/W

Note 2: When mounted on 1 inch square copper board $t \le 10$ sec The value in any given application depends on the user's specific board design.

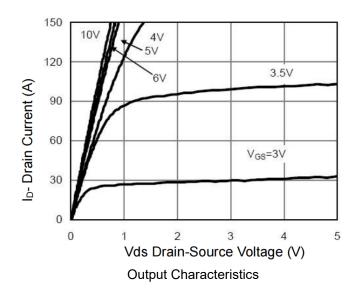
6.Electrical Characteristics at Ta=25°C (Note 3)

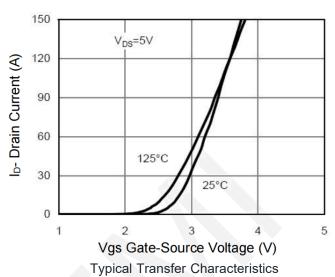
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V _{(BR)DSS}	$I_D = 250 \mu A$, $V_{GS} = 0 V$	40	-	-	V
Zero-Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} = 0V	-	-	1	μΑ
Gate to Source Leakage Current	Igss	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} , I _{DS} =250µA	1.0	1.6	2.5	V
Static Drain to Source On-State	-	I _D =20A, V _{GS} = 10V	-	5.8	7.5	mΩ
Resistance	R _{DS(on)}	I _D = 10A, V _{GS} = 4.5V	-	7.3	11	mΩ
Input Capacitance	C _{iss}	V _{GS} =0V,	-	2689	-	pF
Output Capacitance	Coss	V _{DS} =15V,	-	483	-	pF
Reverse Transfer Capacitance	Crss	Frequency=1.0MHz	-	189	-	pF
Turn-ON Delay Time	t _{d(on)}	$V_{DD} = 20V, R_L = 1\Omega,$ $V_{GS} = 10V, I_D = 30A,$ $R_{GEN} = 3\Omega$	-	15	-	ns
Rise Time	tr		-	18	-	ns
Turn-OFF Delay Time	t _{d(off)}		-	52	-	ns
Fall Time	tf		-	23	-	ns
	Qg	V _{DS} =20V, V _{GS} = 10V, I _D =30A	-	75	-	nC
Total Gate Charge	Qgs		-	10.5	-	nC
	Q _{gd}		-	17	-	nC
Diode Forward Voltage	V_{FSD}	I _S =30A, V _{GS} = 0	-	-	1.2	V

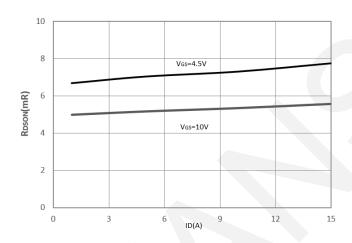
Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



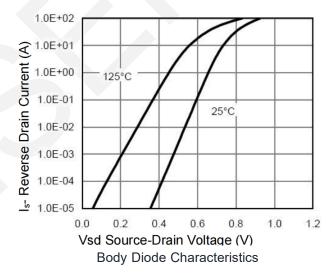
7. Typical electrical and thermal characteristics

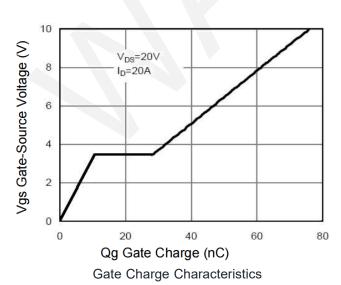


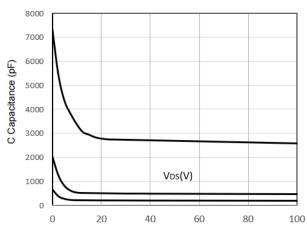




On-resistance vs. Drain Current

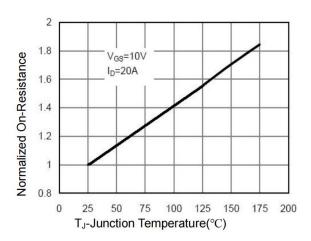






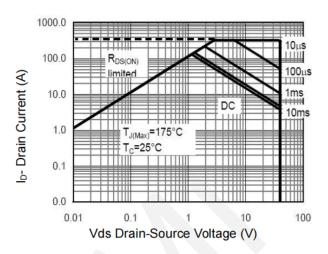
Capacitance Characteristics



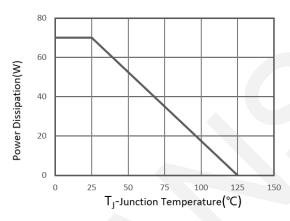


Normalized on Resistance vs.

Junction Temperature

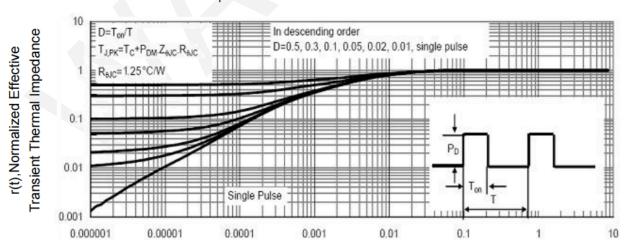


Maximum Safe Operating Area



Maximum Continuous Drain Current vs.

Case Temperature

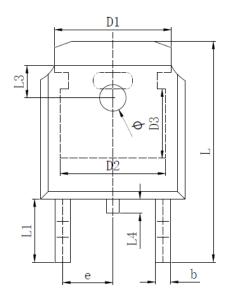


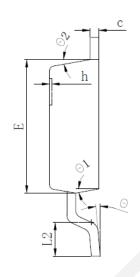
Square Wave Pluse Duration(sec)

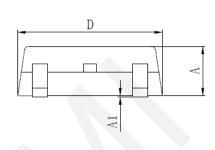
Maximum Effective Transient Thermal Impedance, Junction-to-Case



8.Package Dimensions







SYMBOL		MILLIMETER	
	MIN	Тур.	MAX
A	2. 200	2. 300	2. 400
A1	0.000		0. 127
b	0. 640	0.690	0.740
c(电镀后)	0. 460	0.520	0. 580
D	6. 500	6. 600	6. 700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
Е	6. 000	6. 100	6. 200
е	2.286 TYP		
h	0.000	0. 100	0. 200
L	9. 900	10. 100	10. 300
L1	2.888 REF		
L2	1. 400	1. 550	1. 700
L3	1.600 REF		
L4	0.600	0.800	1. 000
ф	1. 100	1. 200	1. 300
θ	0°		8°
θ 1	9° TYP		
θ 2	9° TYP		



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